

REMARKS

The office action of February 1, 2005, has been carefully considered.

It is noted that claims 1, 6, 7, 9, 11 and 15 are rejected under 35 U.S.C. 102(e) over the patent to Hwang et al.

Claim 2 is rejected under 35 U.S.C. 103(a) over Hwang et al. in view of the patent to O'Mara et al.

Claim 3 is rejected under 35 U.S.C. 103(a) over Hwang et al. in view of the patent to Wytman et al.

Claims 4 and 12 are rejected under 35 U.S.C. 103(a) over Hwang et al. in view of the patent to Morita et al.

Claims 8 and 14 are rejected under 35 U.S.C. 103(a) over Hwang et al. in view of the patent to Brown.

Finally, it is noted that claims 5, 10, 13 and 16 would be allowable if rewritten in independent form.

In view of the Examiner's rejections of the claims, applicant has amended claims 1-12 and 16.

It is respectfully submitted that the claims presently on file differ essentially and in an unobvious, highly advantageous manner from the constructions disclosed in the references.

Turning now to the references and particularly to the patent to Hwang et al., it can be seen that this patent discloses a method for transporting and electrostatically chucking a semiconductor wafer. Hwang et al. disclose a permanent voltage supply, whereas in the presently claimed invention there is no additional external power supply. In Hwang et al., the wafer is connected directly with a pole of the voltage source (see Figs. 2 and 3, in particular the arrow pointing upward in the component 34). The remaining figures also all show a voltage source. Thus, due to the permanent connection to the voltage source it is not possible for Hwang et al. to disclose a transportable electrostatic chuck, as in the presently claimed invention.

In view of these considerations it is respectfully submitted

that the rejection of claims 1, 6, 7, 9, 11 and 15 under 35 U.S.C. 102(e) over the above-discussed reference is overcome and should be withdrawn.

The patent to O'Mara et al. discloses an article comprising a diffuser with flow control features. This reference has nothing to do with processing wafers. This patent is intended for use in making pills or tablets using electrostatic forces.

The Examiner combined O'Mara et al. with Hwang et al. in determining that claim 2 would be unpatentable over such a combination. Applicant respectfully submits that these references deal with completely different technologies and a person skilled in the art of semiconductor wafer manufacturing would have no motivation to look to the teachings of a patent for making pharmaceuticals. Thus, there is no motivation for combining the references as argued by the Examiner. Furthermore, even if the references are combinable, the combination does not teach no additional external power supply and a transportable electrostatic chuck, as in the presently claimed invention.

In view of these considerations it is respectfully submitted that the rejection of claim 2 under 35 U.S.C. 103(a) over a

combination of the above-discussed references is overcome and should be withdrawn.

The patent to Wytman et al. discloses a water lift mechanism with electrostatic pickup. Wytman et al. do teach an inductive coupling. However, a permanent voltage supply is present. In Fig. 4 the chuck arrangement is fixedly connected to the voltage source, which is required due to the various currents from zero.

The Examiner combined Wytman et al. with Hwang et al. in determining that claim 3 would be unpatentable over such a combination. Applicant respectfully submits that the combination does not teach no additional external power supply and a transportable electrostatic chuck, as in the presently claimed invention.

In view of these considerations it is respectfully submitted that the rejection of claim 3 under 35 U.S.C. 103(a) over a combination of the above-discussed references is overcome and should be withdrawn.

The patent to Morita et al. discloses an electrostatic chuck in which when the wafer is held, the wafer is permanently

connected to the pole of a voltage source, see Figs. 2, 3C, 4C and 4D. The connection is provided by the element 46, see column 2, line 6. Mobility as defined in the claims presently on file is not possible in Morita et al.

The Examiner combined Morita et al. with Hwang et al. in determining that claims 4 and 12 would be unpatentable over such a combination. Applicant respectfully submits that the combination does not teach no additional external power supply and a transportable electrostatic chuck, as in the presently claimed invention.

In view of these considerations it is respectfully submitted that the rejection of claims 4 and 12 under 35 U.S.C. 103(a) over a combination of the above-discussed references is overcome and should be withdrawn.

The patent to Brown discloses the monitoring of wafer presence and position in semiconductor processing operations. This patent also shows a permanent supply of voltage, in particular see Fig. 1 and column 4, beginning with line 23.

The Examiner combined brown with Hwang et al. in determining

that claims 8 and 14 would be unpatentable over such a combination. Applicant respectfully submits that the combination does not teach no additional external power supply and a transportable electrostatic chuck, as in the presently claimed invention.

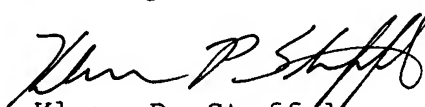
In view of these considerations it is respectfully submitted that the rejection of claims 8 and 14 under 35 U.S.C. 103(a) over a combination of the above-discussed references is overcome and should be withdrawn

Reconsideration and allowance of the present application are respectfully requested.

Any additional fees or charges required at this time in connection with this application may be charged to Patent and Trademark Office Deposit Account No. 11-1835.

Respectfully submitted,

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Dated: April 27, 2005

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, PO Box 1450 Alexandria, VA 22313-1450, on April 27, 2005.

By: 
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Date: April 27, 2005